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PC817 Series

High Density Mounting Type Photocoupler

- * Lead forming type (I type) and taping reel type (P type) are also available. (PC817I/PC817P)
- ** TÜV (VDE0884) approved type is also available as an option.

■ Features

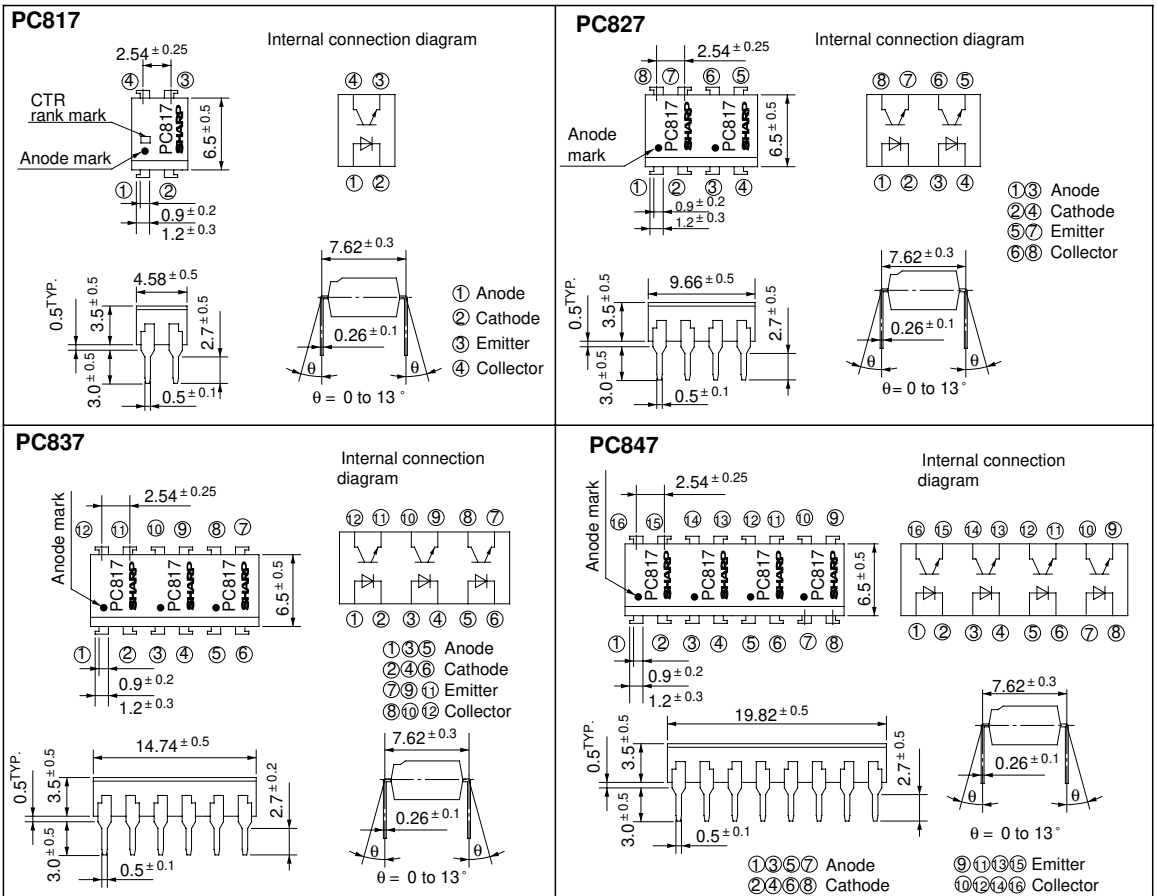
1. Current transfer ratio
(CTR: MIN. 50% at $I_F = 5\text{mA}$, $V_{CE} = 5\text{V}$)
2. High isolation voltage between input and output ($V_{iso} : 5\,000\text{V}_{rms}$)
3. Compact dual-in-line package
PC817 : 1-channel type
PC827 : 2-channel type
PC837 : 3-channel type
PC847 : 4-channel type
4. Recognized by UL, file No. E64380

■ Applications

1. Computer terminals
2. System appliances, measuring instruments
3. Registers, copiers, automatic vending machines
4. Electric home appliances, such as fan heaters, etc.
5. Signal transmission between circuits of different potentials and impedances

■ Outline Dimensions

(Unit : mm)



Absolute Maximum Ratings

(T_a = 25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	50	mA
	*1 Peak forward current	I _{FM}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _C	50	mA
	Collector power dissipation	P _C	150	mW
Total power dissipation		P _{tot}	200	mW
*2 Isolation voltage		V _{iso}	5 000	V _{rms}
Operating temperature		T _{opr}	- 30 to + 100	°C
Storage temperature		T _{stg}	- 55 to + 125	°C
*3 Soldering temperature		T _{sol}	260	°C

*1 Pulse width ≤ 100μs, Duty ratio : 0.001

*2 40 to 60% RH, AC for 1 minute

*3 For 10 seconds

Electro-optical Characteristics

(T_a = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V _F	I _F = 20mA	-	1.2	1.4	V
	Peak forward voltage	V _{FM}	I _{FM} = 0.5A	-	-	3.0	V
	Reverse current	I _R	V _R = 4V	-	-	10	μA
	Terminal capacitance	C _t	V = 0, f = 1kHz	-	30	250	pF
Output	Collector dark current	I _{CEO}	V _{CE} = 20V	-	-	10 ⁻⁷	A
Transfer characteristics	*4 Current transfer ratio	CTR	I _F = 5mA, V _{CE} = 5V	50	-	600	%
	Collector-emitter saturation voltage	V _{CE(sat)}	I _F = 20mA, I _C = 1mA	-	0.1	0.2	V
	Isolation resistance	R _{ISO}	DC500V, 40 to 60% RH	5 × 10 ¹⁰	10 ¹¹	-	Ω
	Floating capacitance	C _f	V = 0, f = 1MHz	-	0.6	1.0	pF
	Cut-off frequency	f _c	V _{CE} = 5V, I _C = 2mA, R _L = 100Ω, - 3dB	-	80	-	kHz
Response time	Rise time	t _r	V _{CE} = 2V, I _C = 2mA, R _L = 100Ω	-	4	18	μs
	Fall time	t _f		-	3	18	μs

*4 Classification table of current transfer ratio is shown below.

Model No.	Rank mark	CTR (%)
PC817A	A	80 to 160
PC817B	B	130 to 260
PC817C	C	200 to 400
PC817D	D	300 to 600
PC8 [※] 7AB	A or B	80 to 260
PC8 [※] 7BC	B or C	130 to 400
PC8 [※] 7CD	C or D	200 to 600
PC8 [※] 7AC	A, B or C	80 to 400
PC8 [※] 7BD	B, C or D	130 to 600
PC8 [※] 7AD	A, B, C or D	80 to 600
PC8 [※] 7	A, B, C, D or No mark	50 to 600

※ : 1 or 2 or 3 or 4

Fig. 1 Forward Current vs. Ambient Temperature

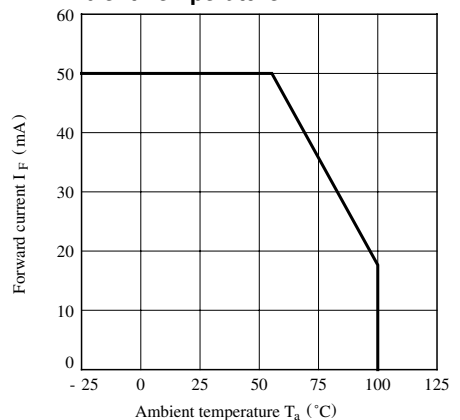


Fig. 2 Collector Power Dissipation vs. Ambient Temperature

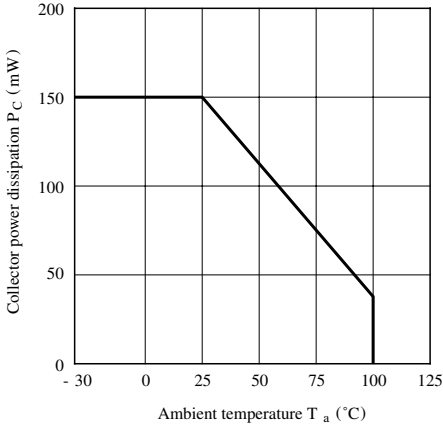


Fig. 3 Peak Forward Current vs. Duty Ratio

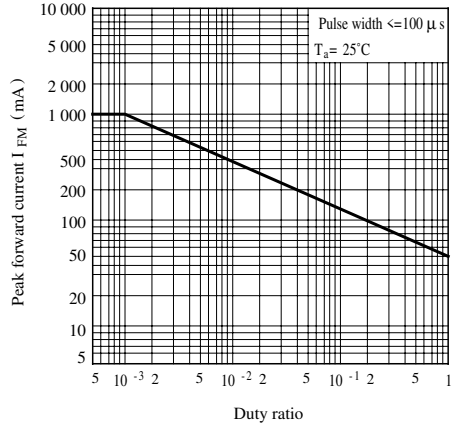


Fig. 4 Current Transfer Ratio vs. Forward Current

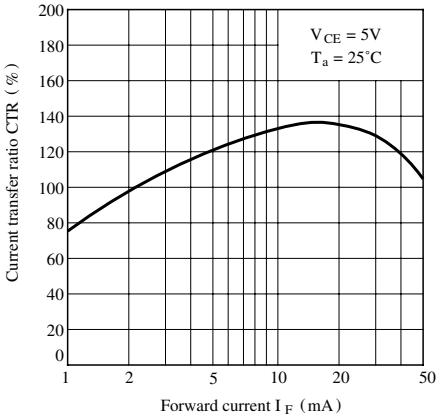


Fig. 5 Forward Current vs. Forward Voltage

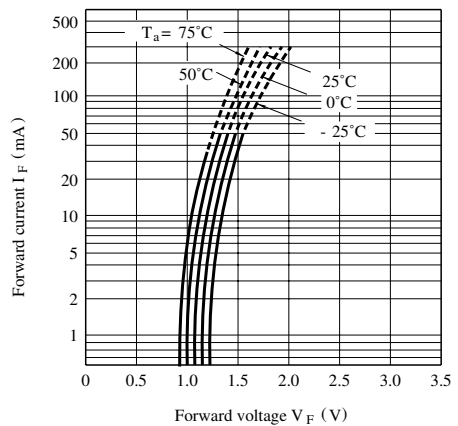


Fig. 6 Collector Current vs. Collector-emitter Voltage

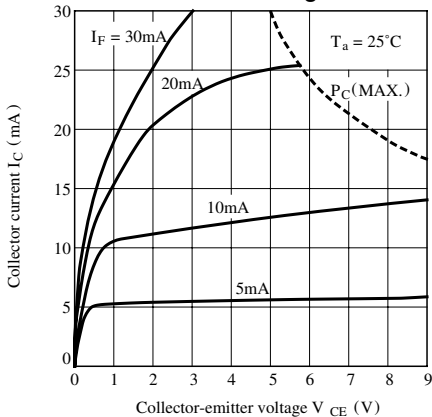


Fig. 7 Relative Current Transfer Ratio vs. Ambient Temperature

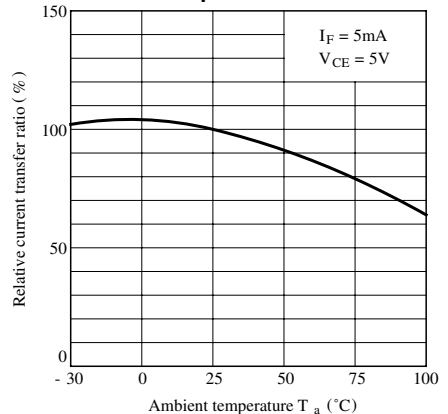


Fig. 8 Collector-emitter Saturation Voltage vs. Ambient Temperature

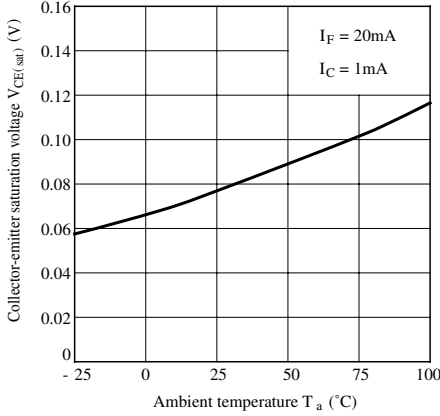


Fig. 9 Collector Dark Current vs. Ambient Temperature

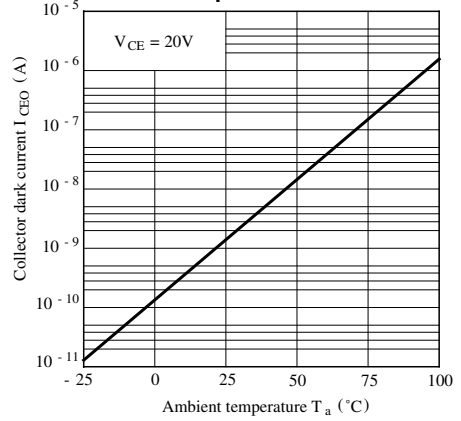


Fig.10 Response Time vs. Load Resistance

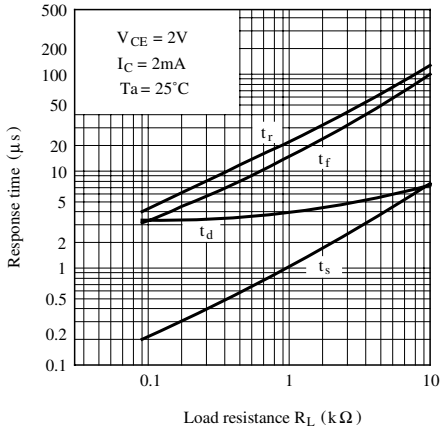
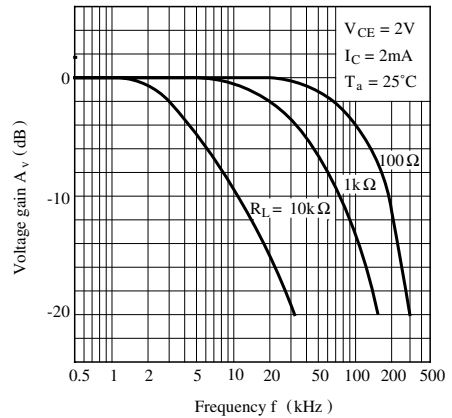
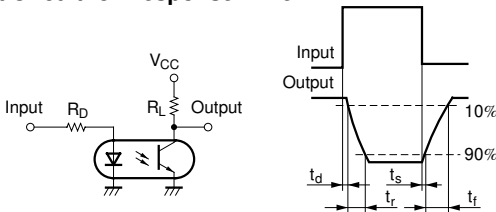


Fig.11 Frequency Response



Test Circuit for Response Time



Test Circuit for Frequency Response

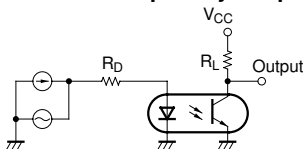
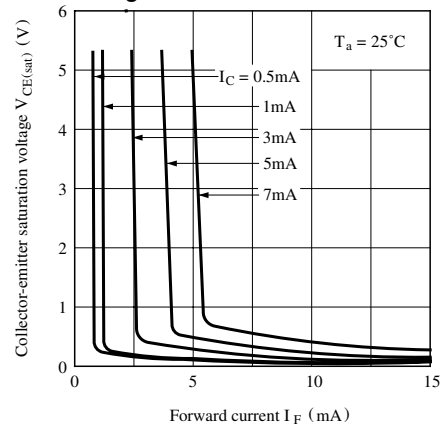


Fig.12 Collector-emitter Saturation Voltage vs. Forward Current



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